

04-11-2002



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To the Honorable Commissioner of Patents and Trademarks, attached original documents or copy thereof.

1. Name of conveying party(ies):

Thomas L. Sly
Kevin M. Quinn

3-26-02

2. Name and address of receiving party(ies):

Name: **High Connection Density, Inc.**

Internal Address:

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Street Address: **1267 Borregas Avenue**

City: **Sunnyvale** State: **CA** ZIP: **94089**

Execution Date: **3/5/13**

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/645,858

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Mark Levy**

Internal Address: **SALZMAN & LEVY**

Press Building - Ste. 902

Street Address: **19 Chenango Street**

City: **Binghamton**

State: **NY** ZIP: **13901**

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ **40.00**

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☒ Authorized to be charged to deposit account

8. Deposit account number:

19-0077

(Attach duplicate copy of this page if paying by deposit account)

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark Levy

Name of Person Signing

Signature

3/20/02

Date

Total number of pages including cover sheet, attachments, and document:

3

**Assignment of Rights, Title and Interest in Invention
(Multiple inventors; single assignee)**Docket No.
HCD-205*This is an Assignment of the following rights, title and interest: (check all that apply):*☐ *United States of America rights, title and interest in the invention*☐ *Foreign rights, title and interest in the invention*☒ *United States Patent Application Serial No. 09/645,858**Date of Execution:* _____*Date of Filing:* 8/24/00☐ *United States Provisional Patent Application Serial No.* _____☐ *United States Patent No(s).* _____☐ *International (PCT) Patent Application Serial No.* _____☐ *Other (specify)* _____**Title of the Invention**

HIGH CAPACITY MEMORY MODULE WITH HIGHER DENSITY AND IMPROVED MANUFACTURABILITY

Inventors (assignors)

<i>Name</i>	<i>Address</i>
Thomas L. Sly	8829 West Shellman Drive, Cicero, New York 13039
Kevin M. Quinn	148 Loma Avenue, Syracuse, New York 13208

Assignee

<i>Name</i>	<i>Address</i>
High Connection Density, Inc.	1267 Borregas Avenue Sunnyvale, California 94089

